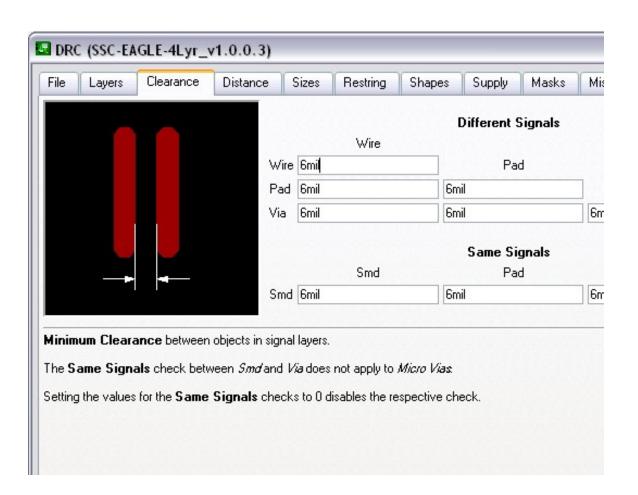


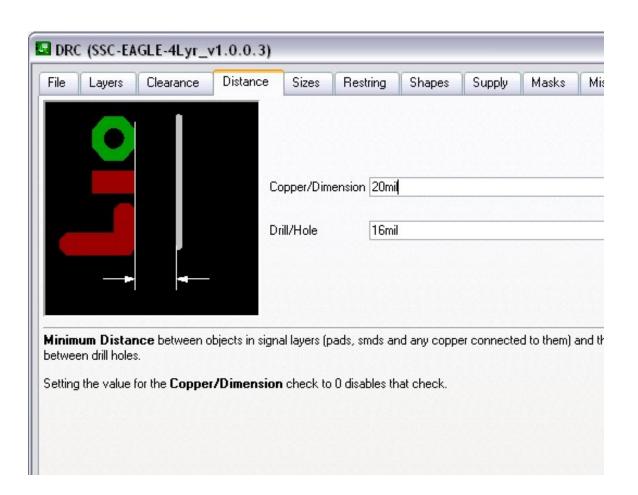


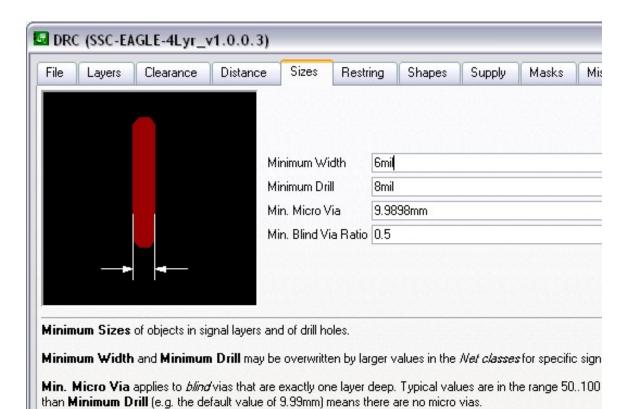
Layers are combined through either *core* or *prepreg* material. **a*b** combines layers a and b with a *core*, while **a** *prepreg*.

Buried and **through** vias are defined by writing (. . .).

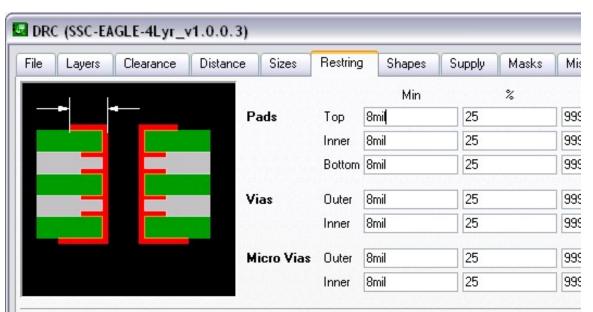
Blind vias are defined by writing [t:...:b], which defines a blind via from top to layer / and from bottom to **Example**: [2:1+((2*3)+(4*16))] is a multilayer setup with two cores, combining layers 2/3 and 4/16, vias going through both cores. The cores are combined through a prepreg and buried vias are produced throu Finally layer 1 is added, with blind vias going from layer 1 to 2.







Min. Blind Via Ratio defines the minimum drill diameter d a blind via must have if it goes through a layer of t manufacturers usually give this "aspect ratio" in the form 1:0.5, where 0.5 would be the value that has to b



Restrings for pads and vias are defined in percent of the drill diameter (limited by **Min** and **Max**). If the diame via would result in a larger restring, that value will be used in the outer layers.

If the Diameter option is checked the actual pad or via diameter will be taken into account in the inner layers

Micro Vias are *blind* vias that are exactly one layer deep and have a drill diameter that is smaller than the **Mi** defined under *Sizes* (which may be overwritten by a larger **Drill** value in the *Net classes*).

